AWH DETROIT 2024



October 28 & 29, 2024 Detroit, USA

## Main Topics 2024:

- Architecture Trends
- Quality / Realiability
- Engineering Process
- 48V Standardization / Automation
- Benchmarking / Cost Opportunities

# Top Speakers e.g.:



Dr. Oana Buliga Lead Expert Innovation Management, LEONI Bordnetz-Systeme GmbH



Leena Shah Global LV & HV EDS Core Components & Applications Manager, Ford Motor Company



Robin Hagelmüller Senior Manager LV Architecture / Distribution, Tesla, Inc.



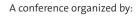
Vasanth Sista Staff Field Application Engineer, TE Connectivity



Paul J. Johnston Portfolio Development Executive, Integrated Electrical Systems, Siemens Digital Industries Software



Simon Wilkinson Senior Specialist Virtual Validation Lead, Yazaki North America







# **AWH DETROIT 2024**



# 1<sup>st</sup> Day: Monday, October 28, 2024

08:30	Arrival of participants, registration, networking in the exhibition area		
09:20	Welcome, opening speech by <b>Georg Sterler</b> , Conference Chairman		
09:30	Challenges in the Wiring Industry: An OEM Perspective Leena Shah, Global LV & HV EDS Core Components & Applications Manager, Ford Motor Company		
10:00	North American Charging Standard – An Overview Ram Kishore Venkatesan, Senior Development Engineer, TE Connectivity		
10:30	SDV – Will the Impact on Wiring mean Decimation for Transportation Harness Manufacturing Businesses? <i>Paul J. Johnston</i> , Portfolio Development Executive, Integrated Electrical Systems, Siemens Digital Industries Software		
11:00	Coffee Break & Networking in the Exhibition		
11:30	<b>48V Standardization / Automation</b> <i>Robin Hagelmüller,</i> Senior Manager LV Architecture / Distribution, Tesla, Inc.		
12:00	Considerations for Wiring Harness Development from Ecological Perspective Dr. Oana Buliga, Lead Expert Innovation Management, Advanced Development, LEONI Bordnetz-Systeme GmbH I Wiring Systems Division		
12:30	The Impact of Virtual Validation on EDS Design and Validation Simon Wilkinson, Senior Specialist Virtual Validation Lead, Yazaki Engineering, Yazaki North America		
13:00	Joint Lunch sponsored by Schunk Sonosystems & Networking in the Exhibition		
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#### Afternoon Session chaired by moderator **Senad Melkic**, Director North America, GG Cables and Wires USA, Inc.



**48V Applications** *Vasanth Sista*, *Staff Field Application Engineer*, *TE Connectivity* 

14:30				
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NY.				

#### Latest Trends in Automotive Ethernet STP and Coaxial Cables

Jonathan S. de Sousa, Senior Cable Technology Specialist, GG Group



#### Adding Options beyond Copper – Glass Optical Fiber for Automotive Highspeed Data Links

**Sebastian Dumann**, Business Area Automotive Head of Product Management Data Connector Cable Americas



**Thomas Müller**, R&D Automotive - Data Connector Lead Engineer Systems & Requirements, Rosenberger Hochfrequenztechnik GmbH & Co. KG

15:30	Coffee Break & Networking in the Exhibition	
16:00	Non-alloyed Aluminium for EV busbar Applications Markus Böhm, Process Technology Specialist, Yazaki Systems Technology	
16:30	Measuring CTI above 600V: How to evaluate Material Safety in High Voltage Applications Krijn Dijkstra, Vice President Research & Development, Envalior	
17:00	Charging Parks: Safety-critical Significance of the Wire Inductance for Pyro-fuses Dr. Dietmar Haba, Lead Product Engineer, Astotec Automotive Safety GmbH	
17:30	Get-together with fine food and drinks,	

Networking at its best

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# **AWH DETROIT 2024**



# 2<sup>nd</sup> Day: Tuesday, October 29, 2024



#### Welcome by moderator of first session *Eric Varton*, Vice President of Engineering, Yazaki North America



Machine Learning Approach for Crimp Optimization for High Speed Terminals Balaji Rengarajan, Design Engineer, Molex LLC



Green W/H – Analysis and Potentials for CO2 Reduction on Examples of different W/H Stefan Trippler, Coordinator – Environment & Sustainability, SEI Automotive Europe GmbH



## Are you ready for the Future of Wire Harness Automation?

*Christian Infanger*, Director Product Group Harness Assembly, Komax AG

10:30 Coffee Break & Networking in the Exhibition

Second session chaired by Georg Sterler, Conference Chairman



The Contribution of Tape for Automizing Wire Harnessing Production *Michel Mies*, Director Product Development, tesa site Sparta, tesa tape, inc.



*Nickolas Morrow*, International Product Manager Electrical Systems, tesa tape, inc.



Harness Trends in the Automotive Industry Matthew Schroeder, Chief Engineer Electrical and Electronics, Caresoft Global Technologies, Inc.

12:00	Closing Speech by Georg Sterler, Conference Chairman		
12:10	Joint Lunch sponsored by Telsonic & Networking in the Exhibition	TELSONIC ULTRASONICS	
13:15	Shuttle Service to Caresoft site visit in Livonia		
15:15	Shuttles returning to The Henry, Autograph Collection	Hotel	

# Members of the Advisory Board:



Aaron de Chazal Sr. Manager Resident Engineering, Americas Automotive, TE Connectivity



**Teresa Hegarty** Global Innovation Director, EDS & CS, Aptiv



**Vijy Koshy** Engineering Direcor, Molex



**Co-Chairman: Senad Melkic** Director North America, GG Cables and Wires USA, Inc.



Leena Shah Global LV & HV EDS Core Components & Applications Manager, Ford Motor Company



Chairman: Georg Sterler Former Head of Wire Harness System Development, AUDI AG



Gary Taraski Former Senior Manager Wiring GSSLT, Sub Components, Architecture, General Motors



Peter Van Wordragen Head Product Development Americas, Leoni Wiring Systems Inc.



**Eric Varton** VP of Engineering, Yazaki North America, Inc.

# Please register online www.eds-conference.com

# AWH DETROIT 2024

# **Registration information**

October 28 & 29, 2024

## **Event location & Accomodation**

The Henry, Autograph Collection Fairlane Plaza, 300 Town Center Dr, Dearborn, MI 48126, USA +1 313 441 2000, https://www.behenry.com/

## **Participation fee**

The participation fee for the conference is:				
Early Bird available until September 4	\$1,795			
Regular Ticket (from September 5)	\$1,895			
Group Discount (not to be combined with Early Bird offer!)				
3 people: (15%)	\$1,610 p.p.			
4-7 people: (25%)	\$1,420 p.p.			
8+ people: (30%)	\$1,325 p.p.			
OEM Early Bird (ends September 4)	\$900			
<b>OEM Standard</b> (from September 5)	\$950			

## Services included in the participation fee

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- Participation in the conference
- Conference documentation
- Refreshments in the breaks
- Lunch on both conference days
- Evening event on the first day of the event

## Registration

We request your registration via Internet at **www.eds-conference.com** 

Upon receipt of your written registration, you will be registered as a participant and will receive a written confirmation of registration as well as an invoice, which has to be paid before the to be paid before the start of the event. In case of cancellation after October 14, 2024 or in case of a No-show, the full registration fee will be charged. However, a substitute participant can be named. Cancellations before this date will be charged with 150 € administration fee. Cancellations and registrations must always be made in writing.

The organizer reserves the right to relocate, change or cancel the entire event or individual parts spatially and / or temporally to move, change or cancel at short notice.

## **Sponsors:**













Wire Harness & Cable Connector

# **Exhibitors/Supporters:**



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Registration and Organization

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